

L Number	Hits	Search Text	DB	Time stamp
-	1364	aluminum and sputtering and target and dopant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:04
-	450	aluminum and sputtering and target and dopant and grain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:05
-	399	aluminum and sputtering and target and dopant and grain and @ad<20000328	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:05
-	65	aluminum and sputtering and target and dopant and grain and @ad<20000328 and "physical vapor deposition"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:07
-	115	aluminum with alloy and sputtering and target and dopant and grain and @ad<20000328	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:08
-	805	aluminum with alloy and sputtering and target and grain and @ad<20000328	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:10
-	487	aluminum with alloy and sputtering and target and grain and @pd<19990328	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:13
-	24	aluminum with alloy and sputtering and target and grain and @pd<19990328 and Sc and Ti and Hf and Si	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/18 15:13